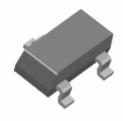
P - Channel Logic Level MOSFET

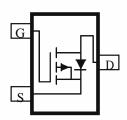
These miniature surface mount MOSFETs utilize High Cell Density process. Low $r_{DS(on)}$ assures minimal power loss and conserves energy, making this device ideal for use in power management circuitry. Typical applications are voltage control small signal switch, power management in portable and battery-powered products such as computer portable electronics and other battery power application.

•	Low r _{DS(on)} Provides Higher Efficiency and
	Extends Battery Life

- Fast Switch
- Low Gate Charge
- Miniature SOT-23 Surface Mount Package Saves Board Space

PRODUCT SUMMARY			
$V_{DS}(V)$	$r_{DS(on)}\left(\Omega\right)$	$I_{D}(A)$	
-30	$0.20 @ V_{GS} = -10 V$	-2.1	
-30	$0.30 @ V_{GS} = -4.5V$	-1.7	





ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C UNLESS OTHERWISE NOTED)					
Parameter			Maximum	Units	
Drain-Source Voltage			-30	V	
Gate-Source Voltage			±20	V	
Continuous Drain Current ^a	T _A =25°C		-2.1		
Continuous Drain Current	$T_A=25^{\circ}C$ $T_A=70^{\circ}C$	1D	-1.7	A	
Pulsed Drain Current ^b			±10		
Continuous Source Current (Diode Conduction) ^a			-0.4	Α	
D	$T_A=25^{\circ}C$	D_	1.25	W	
Power Dissipation ^a	$T_A=25^{\circ}C$ $T_A=70^{\circ}C$	L D	0.8		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Paramete r	Symbol	M aximum	Units		
Maximum Junction-to-Ambient ^a	t <= 5 sec	D	250	°C/W	
	Steady-State	R_{THJA}	285		

Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

(C)

SPECIFICATIONS ($T_A = 25^{\circ}C$ UNLESS OTHERWISE NOTED)							
Parame te r	Symbol	Tank Conditions	Limits			Unit	
rarame ter		Test Conditions	Min	Тур	Max	Omt	
Static							
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = -24 \text{ V}, V_{GS} = 0 \text{ V}$			-1	Ι.Δ	
Zelo Cate voltage Diani Current		$V_{DS} = -24 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55^{\circ}\text{C}$			-10	μA	
Gate-Body Leakage	Igss	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			±100	nA	
Gate-Thres hold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -250 \text{ uA}$	-1.30			V	
On-State Drain Current ^A	ID(on)	$V_{DS} = -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	-3			A	
B i G G B i A		$V_{GS} = -10 \text{ V}, I_{D} = -2.1 \text{ A}$			0.20	Ω	
Drain-Source On-Resistance ^A	fDS(on)	$V_{GS} = -4.5 \text{ V}, I_{D} = -1.7 \text{ A}$			0.30		
Forward Tranconductance ^A	gfs	$V_{DS} = -5 \text{ V}, I_{D} = -2.1 \text{ A}$		2		S	
Diode Forward Voltage	V _{SD}	$I_S = -0.4 \text{ A}, V_{GS} = 0 \text{ V}$		-0.70	-1.2	V	
Dynamic ^b							
Total Gate Charge	Qg	$V_{DS} = -10 \text{ V}, V_{GS} = -5 \text{ V},$		3.4			
Gate-Source Charge	Q_{gs}	$I_{D} = -2.1 \text{ A}$		0.8		nC	
Gate-Drain Charge	Qgd	ID = -2.1 A		1.5			
Turn-On Delay Time	t _{d(on)}			8			
Rise Time t _r		$V_{DS} = -10 \text{ V}, \text{ ID} = -1.1 \text{ A},$		18		ns	
Turn-Off Delay Time	td(off)	$R_G = 50 \Omega$, $V_{GEN} = -10 V$		52		115	
Fall-Time	t_{f}			39			

Notes

- a. Pulse test: $PW \le 300us duty cycle \le 2\%$.
- b. Guaranteed by design, not subject to production testing.

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Typical Electrical Characteristics

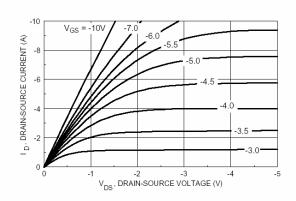


Figure 1. On-Region Characteristics

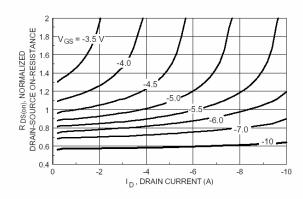


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

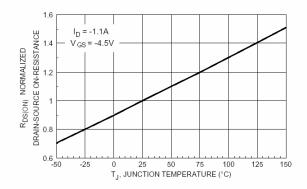


Figure 3. On-Resistance Variation with Temperature

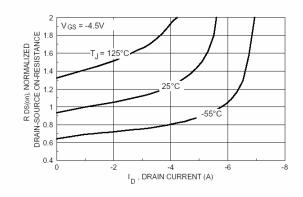


Figure 4. On-Resistance Variation with Gate to Source Voltage

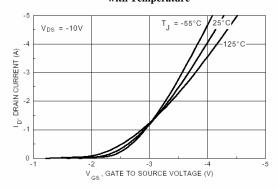


Figure 5. Transfer Characteristics

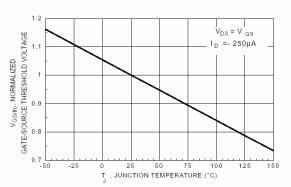


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature



Typical Electrical Characteristics

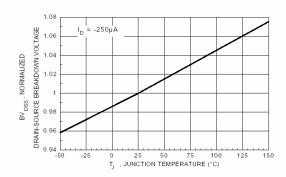


Figure 7. Breakdown Voltage Variation with Temperature.

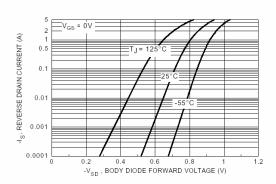


Figure 8. Body Diode Forward Voltage Variation with Source Current and Temperature.

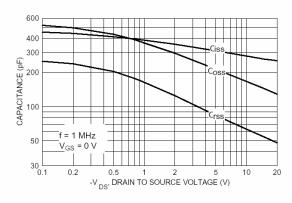


Figure 9. Capacitance Characteristic

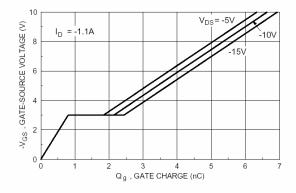


Figure 10. Gate Charge Characteristic

Normalized Thermal Transient Impedance, Junction to Ambient

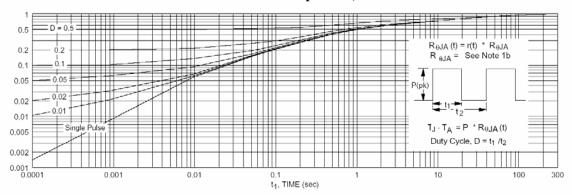


Figure 11. Transient Thermal Response Curve

Typical Electrical Characteristics

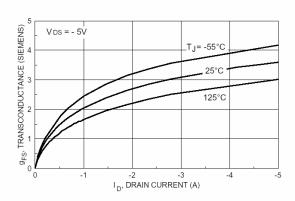
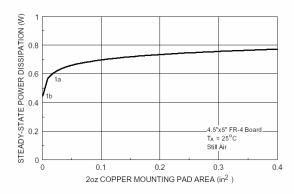


Figure 12. Transconductance Variation With Current & Temperature

Figure 13. Maximum Safe Operation Area



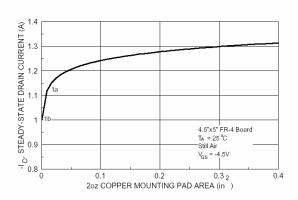


Figure 14. SOT-3 Maximum Steady-State Variation Power Dissipation versus Copper Pad Area

Figure 15. Maximum State-State Drain Current Versus Copper Pad Area

Package Information

